

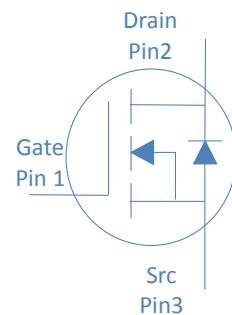
**150V N-Ch Power MOSFET**
**Feature**

- ◊ High Speed Power Smooth Switching, Logic Level
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free

$V_{DS}$	150	V
$R_{DS(on),typ}$   $V_{GS}=10V$	41	mΩ
$I_D$	28	A

**Application**

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ Power Tools
- ◊ UPS
- ◊ Motor Control



Part Number	Package	Marking
HGD480N15M	TO-252	GD480N15M
HGI480N15M	TO-251	GI480N15M

**Absolute Maximum Ratings at  $T_j=25^\circ C$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current	$I_D$	$T_C=25^\circ C$	27.9	A
		$T_C=100^\circ C$	19.7	
Drain to Source Voltage	$V_{DS}$	-	150	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	45	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.4mH, T_C=25^\circ C$	20	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	83	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 175	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{eJC}$	1.8	°C/W
Thermal Resistance Junction-Ambient	$R_{eJA}$	65	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

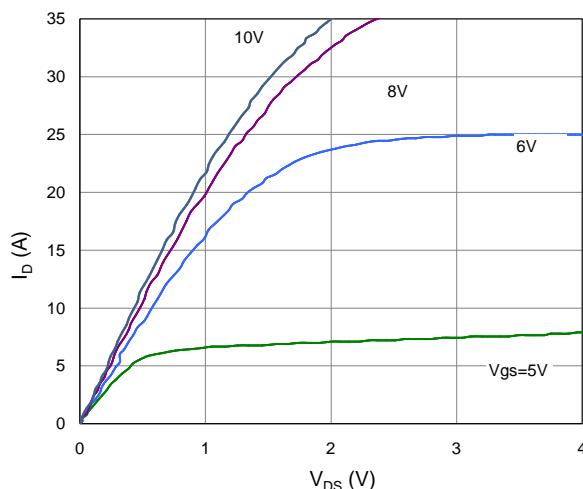
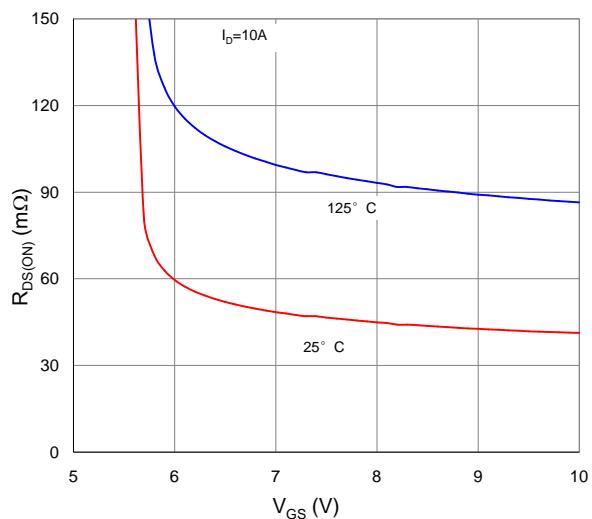
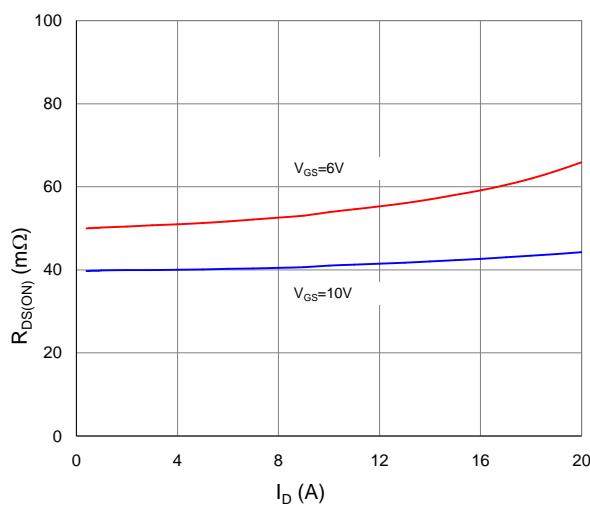
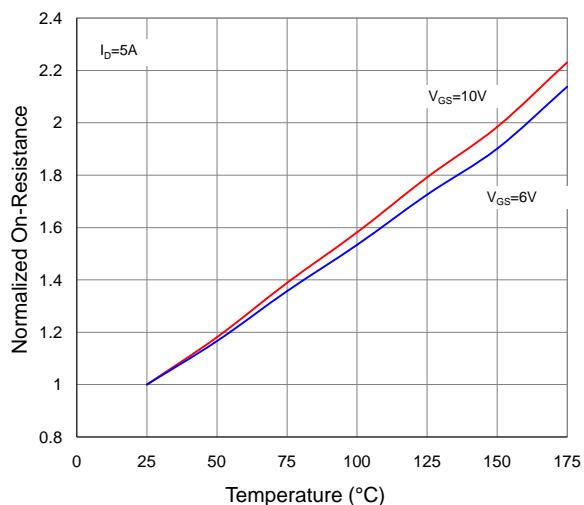
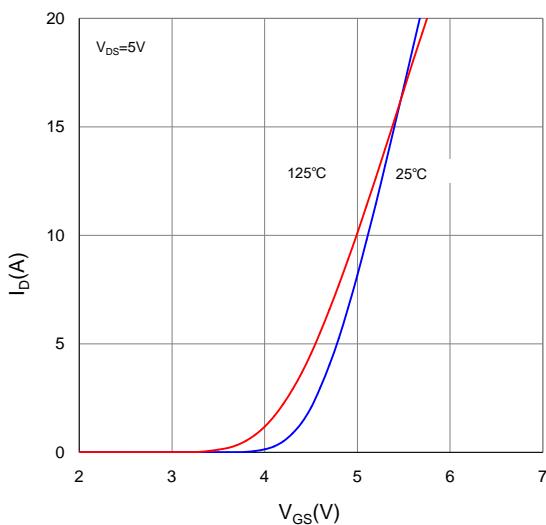
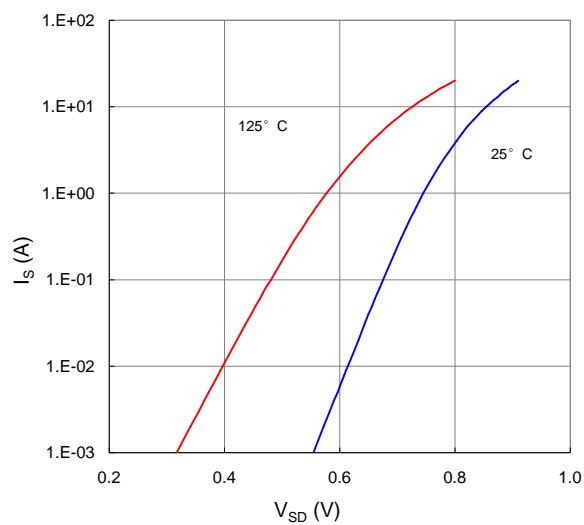
Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	150	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	2	3	4	
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	-	41	48	$\text{m}\Omega$
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_D=10\text{A}$	-	16	-	S
Gate Resistance	$R_G$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	5.9	-	$\Omega$

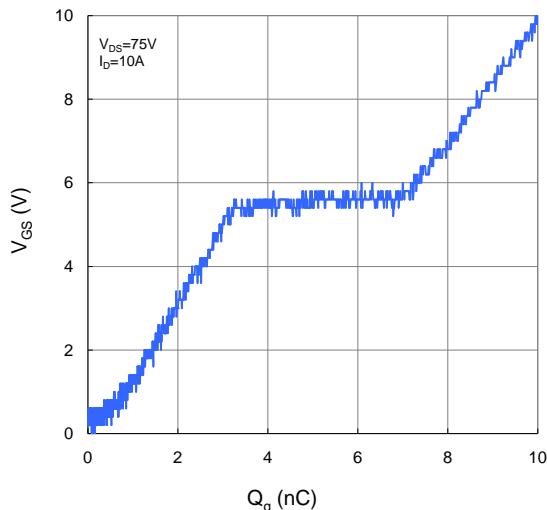
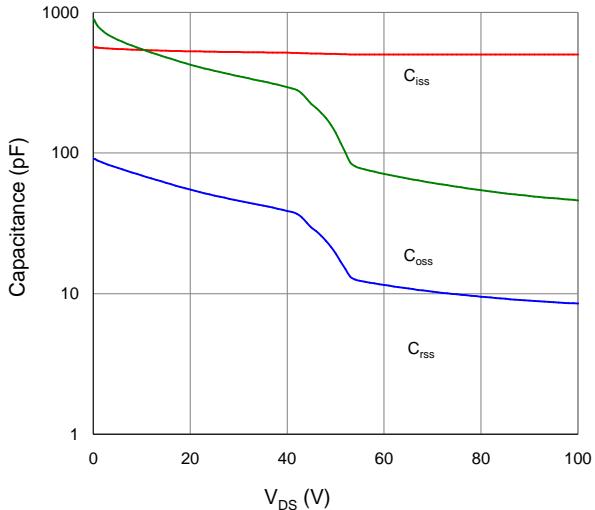
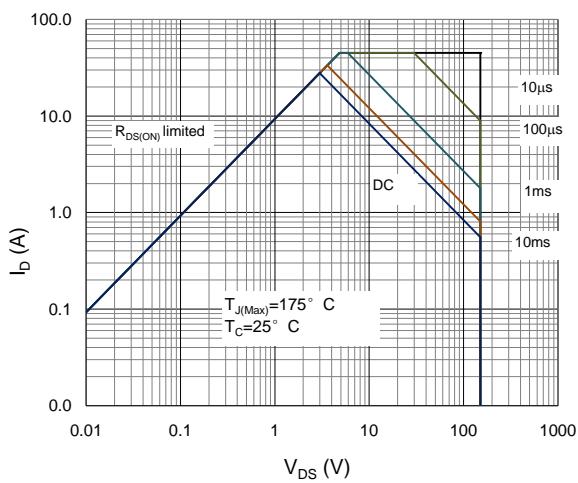
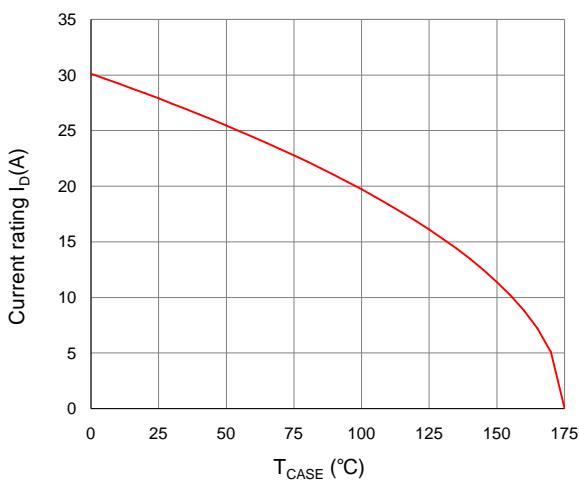
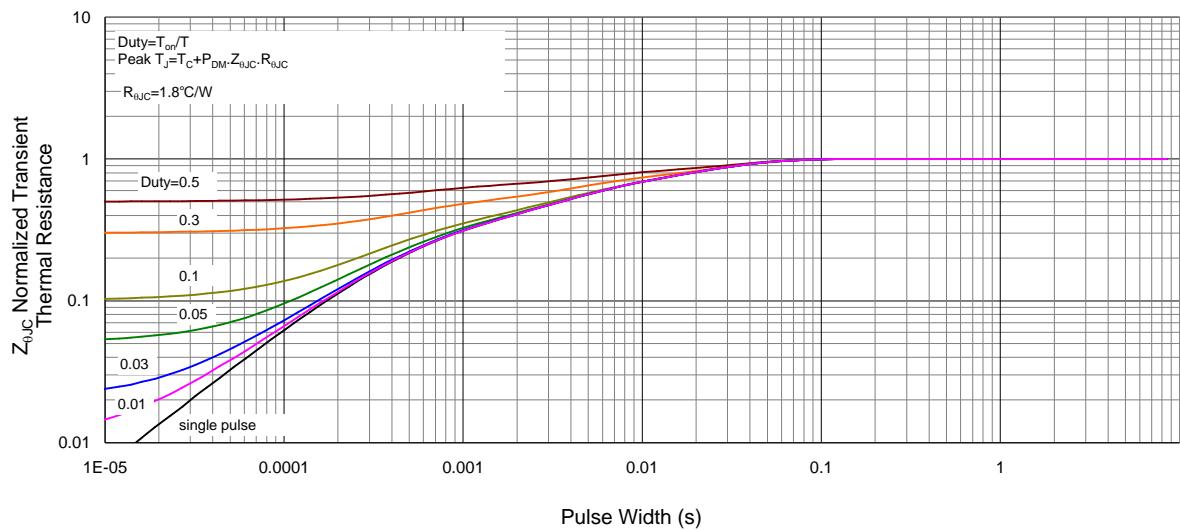
**Dynamic Characteristics**

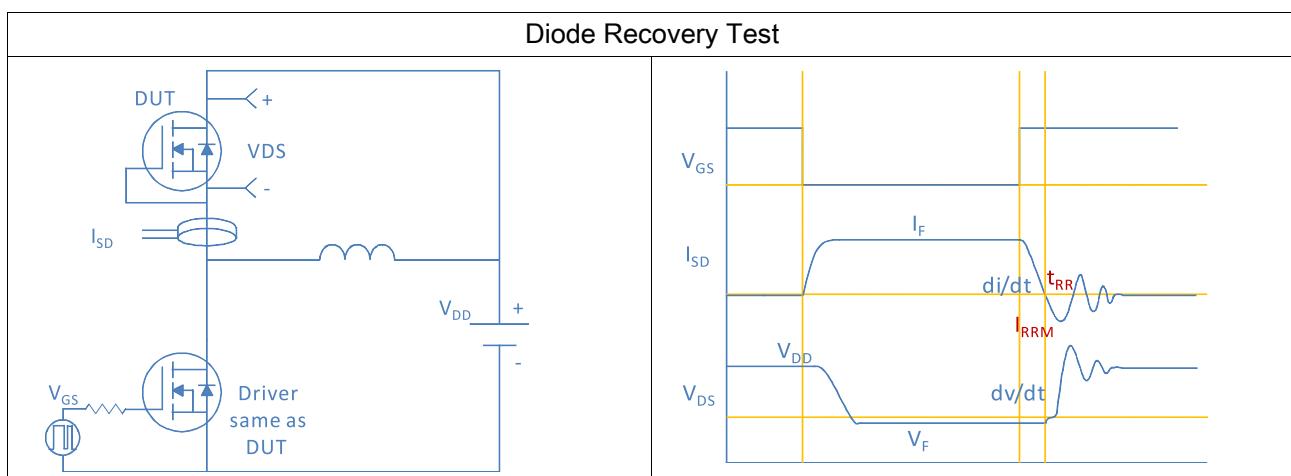
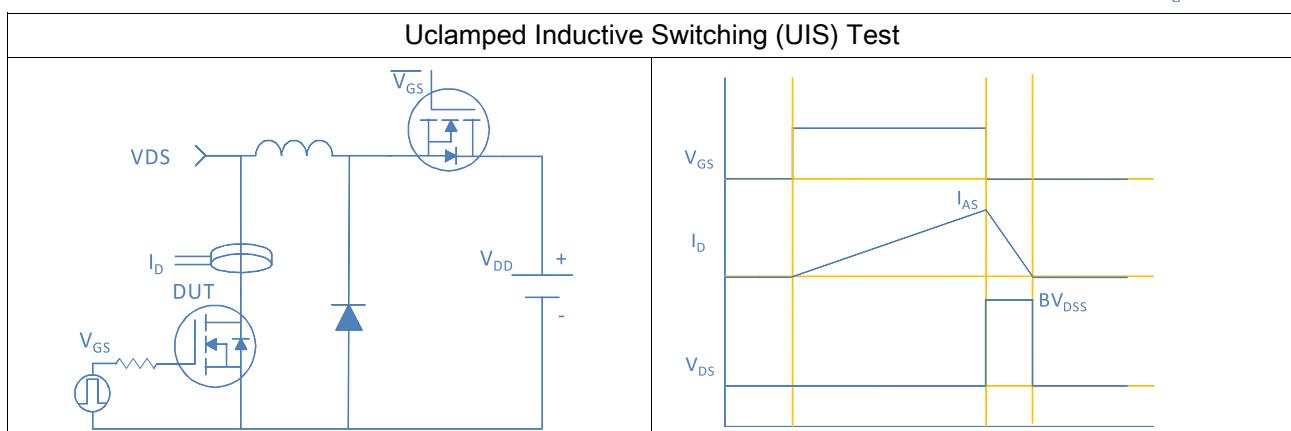
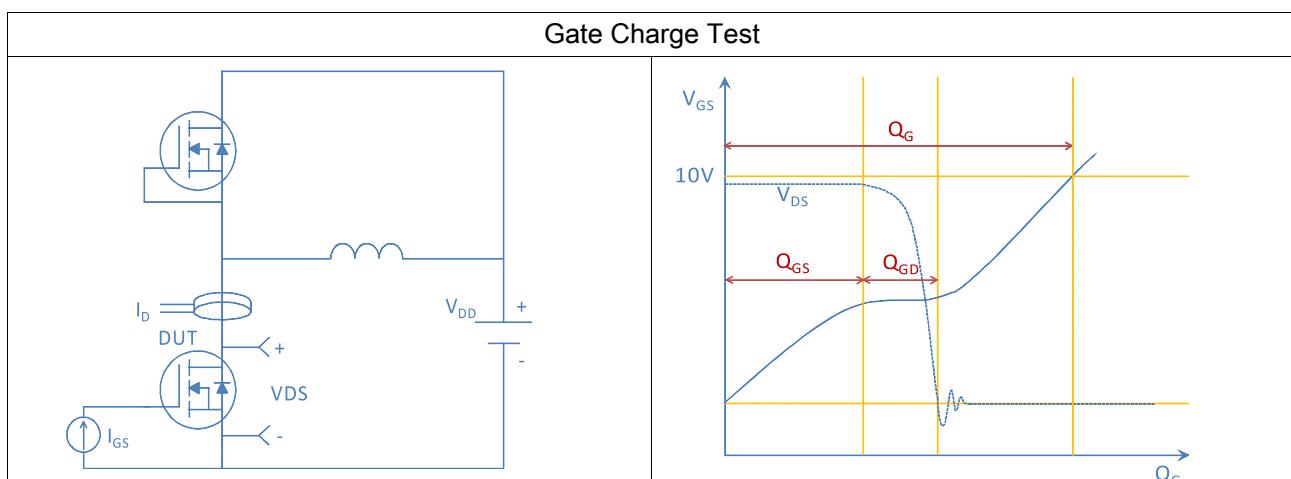
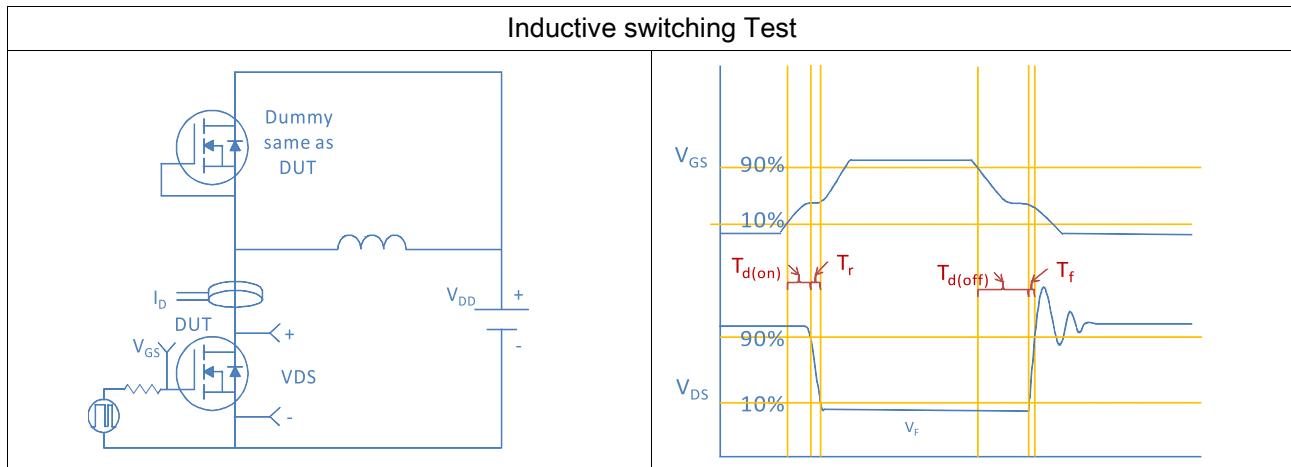
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=75\text{V}, f=1\text{MHz}$	-	500	-	pF
Output Capacitance	$C_{\text{oss}}$		-	57	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	9.9	-	
Total Gate Charge	$Q_g (10\text{V})$	$V_{\text{DD}}=75\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}$	-	10	-	nC
Gate to Source Charge	$Q_{\text{gs}}$		-	3.2	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	3.8	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=75\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}$ , $R_G=10\Omega$ ,	-	11	-	ns
Rise time	$t_r$		-	7	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	12	-	
Fall Time	$t_f$		-	3	-	

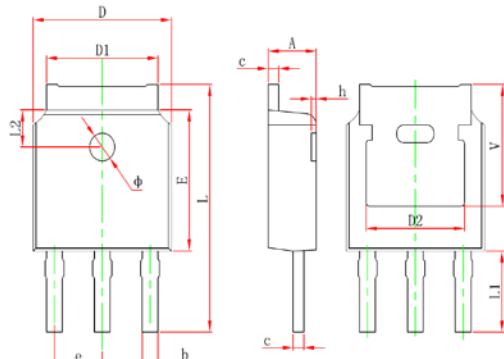
**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R=75\text{V}, I_F=10\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	64	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	96	-	nC

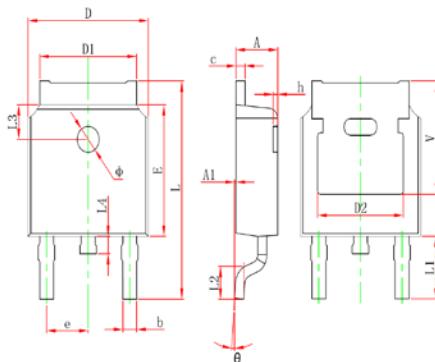
**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case**




**TO-251, 3 leads**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	10.400	11.000	0.409	0.433
L1	3.500 REF.		0.138 REF.	
L2	1.600 REF.		0.063 REF.	
$\Phi$	1.100	1.300	0.043	0.051
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	

**TO-252, 2 leads**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
$\Phi$	1.100	1.300	0.043	0.051
$\theta$	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	